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(21) International Application Number: PCT/US99/12543 (22) International Filing Date: 4 June 1999 (04.06.99) (30) Priority Data: 09/103,416 24 June 1998 (24.06.98) US (71) Applicant: JOHNSON MATTHEY ELECTRONICS, INC. [US/US]; 15128 Euclid Avenue, Spokane, WA 99216 (US). (72) Inventors: PINTER, Michael, R.; East 504 Midway Road, Colbert, WA 99005 (US). DEAN, Nancy, F.; 1827 South Liberty Drive, Liberty Lake, WA 99019 (US). WILLETT, William, B.; South 7220 Cedar Road, Spokane, WA 99224 (US). GETTINGS, Amy; 10923 East 37th, Spokane, WA 99206 (US). SMITH, Charles; 2915 Sunset Hills Road, Escondido, CA 92025 (US). (74) Agent: GIOIA, Vincent, G.; Christie, Parker & Hale, LLP, P.O. Box 7068, Pasadena, CA 91109-7068 (US).		(81) Designated States: CN, JP, KR, SG, European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published With international search report.
(54) Title: TRANSFERRABLE COMPLIANT FIBROUS THERMAL INTERFACE (57) Abstract Described is a transferrable fibrous thermal interface. The interface comprises flocked thermally conductive fibers (32) embedded in an adhesive in substantially vertical orientation with portions of the fibers extending out of the adhesive. An encapsulant (30) fills spaces between the portions of the fibers that extend out of the adhesive (34) and a release liner is on at least one outer surface of the interface.		